

We claim:

1. Molding apparatus for simultaneously molding a molding material around a number of separate substrates, each substrate having a semiconductor chip
 5 mounted thereon, the apparatus comprising a mold housing adapted to have mounted thereon a mold half comprising two mold cavity members, the mold housing comprising a first mold cavity member holding section and a second mold cavity member holding section, the first and second holding sections comprising a common support surface, the support surface including a first
 10 movable member in the first holding section and a second movable member in the second holding section, the first and second movable members being movable between a first position in which they protrude out of the support surface and a second position in which they protrude less from the support surface than in the first position, a first drive mechanism coupled to the first
 15 movable member and a second drive mechanism coupled to the second movable member, the first and second drive mechanisms being independently actuatable to move the first and second movable members between the first and second positions.
- 20 2. Apparatus according to claim 1, wherein the first and second drive mechanisms comprise a linearly movable member coupled to the respective movable member.
3. Apparatus according to claim 2, wherein the linearly movable member is
 25 coupled to the respective movable member by a rotatable member which is

rotatable with respect to the linear movable member and the respective movable member.

4. Apparatus according to claim 2, wherein the linearly movable member is
5 movable substantially perpendicularly to the direction of movement of the respective movable member.

5. Apparatus according to claim 1, wherein the first and second movable
10 members are movable in a direction substantially perpendicular to the common support surface.

6. A mold half comprising a support member, two mold cavity members
movably mounted on the support member for movement relative to the support
direction in a first direction, a mold cavity housing being movably mounted on
15 the support member for movement relative to the support member in a direction substantially parallel to the first direction, and biasing means mounted between the mold cavity housing and the support member to bias the mold cavity housing away from the support member.

20 7. A mold half according to claim 6, further comprising a first mold cavity actuator coupled to the first mold cavity member and a second mold cavity actuator coupled to the second mold cavity member, movement of the actuators moving the respective mold cavity member in the first direction.

8. A mold half according to claim 7, wherein the first and second mold cavity actuators extend through the support member.

9. Molding apparatus for simultaneously molding a molding material around
s a number of separate substrates, each substrate having a semiconductor chip
mounted thereon, the apparatus comprising a mold housing having a mold half
according to claim 6 mounted thereon, the mold housing comprising a first mold
cavity member holding section, in which the first mold cavity member is located,
and a second mold cavity member holding section, in which the second mold
10 cavity member is located, the first and second holding sections comprising a
common support surface on which the support member is located, the support
surface including a first movable member in the first holding section and a
second movable member in the second holding section, the first and second
movable members being coupled to the respective mold cavity member,
15 movement of the first and second movable members moving the respective
mold cavity member in the first direction, a first drive mechanism coupled to the
first movable member and a second drive mechanism coupled to the second
movable member, the first and second drive mechanisms being independently
actuatable to move the first and second movable members between the first
20 and second positions.